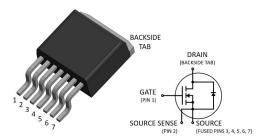
MSC750SMA170SA

1700 V 750 mΩ SiC N-Channel Power MOSFET

Product Overview

The silicon carbide (SiC) power MOSFET product line from Microchip increases the performance over silicon MOSFET and silicon IGBT solutions while lowering the total cost of ownership for high-voltage applications. The MSC750SMA170SA device is a 1700 V, 750 m Ω SiC MOSFET in a TO-263 7-lead package with a source sense.



Features

The following are key features of the MSC750SMA170SA device:

- Low capacitances and low gate charge
- Fast switching speed due to low internal gate resistance (ESR)
- Stable operation at high junction temperature, T_{J(max)} = 175 °C
- · Fast and reliable body diode
- Superior avalanche ruggedness
- RoHS compliant

Benefits

The following are benefits of the MSC750SMA170SA device:

- High efficiency to enable lighter, more compact system
- Simple to drive and easy to parallel
- · Improved thermal capabilities and lower switching losses
- Eliminates the need for external freewheeling diode
- · Lower system cost of ownership

Applications

The MSC750SMA170SA device is designed for the following applications:

- · PV inverter, converter, and industrial motor drives
- · Smart grid transmission and distribution
- Induction heating and welding
- H/EV powertrain and EV charger
- Power supply and distribution

1. Device Specifications

This section shows the specifications of the MSC750SMA170SA device.

1.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings of the MSC750SMA170SA device.

Table 1-1. Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
V _{DSS}	Drain source voltage	1700	V
I _D	Continuous drain current at T _C = 25 °C		Α
	Continuous drain current at T _C = 100 °C	5	
I _{DM}	Pulsed drain current ¹	12	
V _{GS}	Gate-source voltage	23 to -10	V
P _D	Total power dissipation at T _C = 25 °C	64	W
	Linear derating factor	0.425	W/°C

Note:

1. Repetitive rating: pulse width and case temperature limited by maximum junction temperature.

The following table shows the thermal and mechanical characteristics of the MSC750SMA170SA device.

Table 1-2. Thermal and Mechanical Characteristics

Symbol	Characteristic/Test Conditions	Min	Тур	Max	Unit
$R_{\theta JC}$	Junction-to-case thermal resistance		1.57	2.35	°C/W
T_J	Operating junction temperature	- 55		175	°C
T _{STG}	Storage temperature	- 55		150	°C
T _L	Soldering temperature for 10 seconds (1.6 mm from case)			260	°C
Wt	Package weight		0.05		oz
			1.42		g

1.2 Electrical Performance

The following table shows the static characteristics of the MSC750SMA170SA device. T_J = 25 °C unless otherwise specified.

Table 1-3. Static Characteristics

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 100 \mu\text{A}$	1700			V
R _{DS(on)}	Drain-source on resistance ¹	V _{GS} = 20 V, I _D = 2.5 A		750	940	mΩ
V _{GS(th)}	Gate-source threshold voltage	$V_{GS} = V_{DS}, I_{D} = 100 \mu A$	1.9	3.25		V

continued						
Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
$\Delta V_{GS(th)}/$ ΔT_J	Threshold voltage coefficient	$V_{GS} = V_{DS}$, $I_D = 100 \mu A$		-5.7		mV/°C
I _{DSS}	Zero gate voltage drain current	V _{DS} = 1700 V, V _{GS} = 0 V			100	μΑ
		V _{DS} = 1700 V, V _{GS} = 0 V, T _J = 125 °C			500	
I _{GSS}	Gate-source leakage current	V _{GS} = 20 V/–10 V			±100	nA

Note:

1. Pulse test: pulse width < 380 μ s, duty cycle < 2%.

The following table shows the dynamic characteristics of the MSC750SMA170SA device. T_J = 25 °C unless otherwise specified.

Table 1-4. Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
C _{iss}	Input capacitance	V _{GS} = 0 V, V _{DD} = 1360 V, V _{AC} = 25		184		pF
C _{rss}	Reverse transfer capacitance	mV		2		
C _{oss}	Output capacitance			14		
Q _g	Total gate charge	$V_{GS} = -5 \text{ V/20 V}, V_{DD} = 1200 \text{ V}, I_{D}$		11		nC
Q _{gs}	Gate-source charge	= 2.5 A		2.9		
Q _{gd}	Gate-drain charge			2.1		
t _{d(on)}	Turn-on delay time	V_{DD} = 1200 V, V_{GS} = -5 V/20 V, I_{D}		13		ns
t _r	Voltage rise time	= 5 A, $R_{g(ext)}$ = 8 Ω , Freewheeling diode = MSC750SMA170SA (V_{GS}		12		
t _{d(off)}	Turn-off delay time	= –5 V); reference Fig. 1-20		7		
t _f	Voltage fall time			8		
E _{on}	Turn-on switching energy			140		μJ
E _{off}	Turn-off switching energy			17		
ESR	Equivalent series resistance	f = 1 MHz, 25 mV, drain short		2.89		Ω
SCWT	Short circuit withstand time	V _{DS} = 1200 V, V _{GS} = 20 V		2.5		μs
E _{AS}	Avalanche energy, single pulse	V_{DS} = 150 V, , V_{GS} = 20 V, I_{D} = 2.5 A		360		mJ

The following table shows the body diode characteristics of the MSC750SMA170SA device. T_J = 25 °C unless otherwise specified.

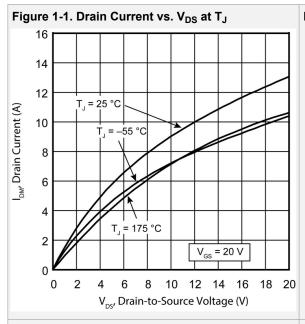
Table 1-5. Body Diode Characteristics

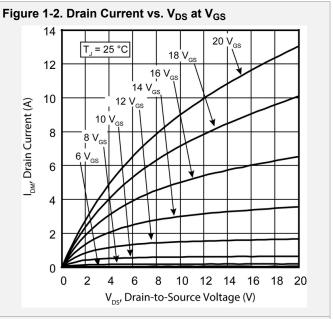
Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
V _{SD}	Diode forward voltage	I _{SD} = 2.5 A, V _{GS} = 0 V		3.8		V
		$I_{SD} = 2.5 \text{ A}, V_{GS} = -5 \text{ V}$		3.9		

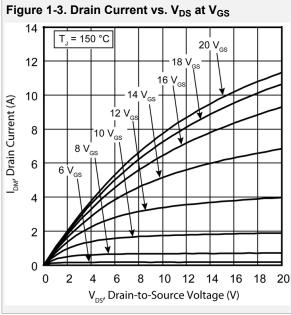
continued						
Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
t _{rr}	Reverse recovery time	$I_{SD} = 5 \text{ A}, V_{GS} = -5 \text{ V}, V_{DD}$		8.6		ns
Q _{rr}	Reverse recovery charge	= 1200 V, dl/dt = –4000 A/μs, Drive Rg = 8 Ω		128		nC
I _{RRM}	Reverse recovery current			22		Α

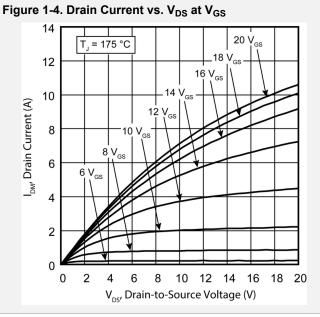
1.3 Typical Performance Curves

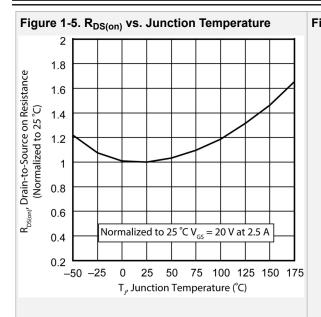
This section shows the typical performance curves of the MSC750SMA170SA device.











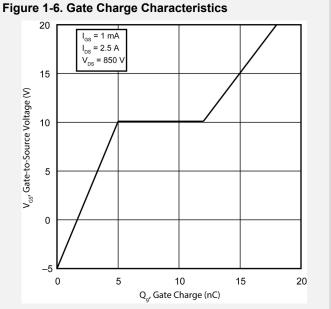
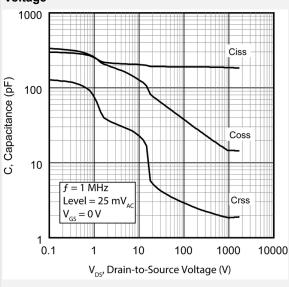
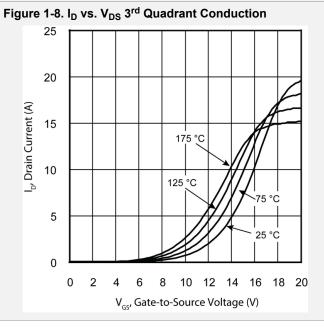
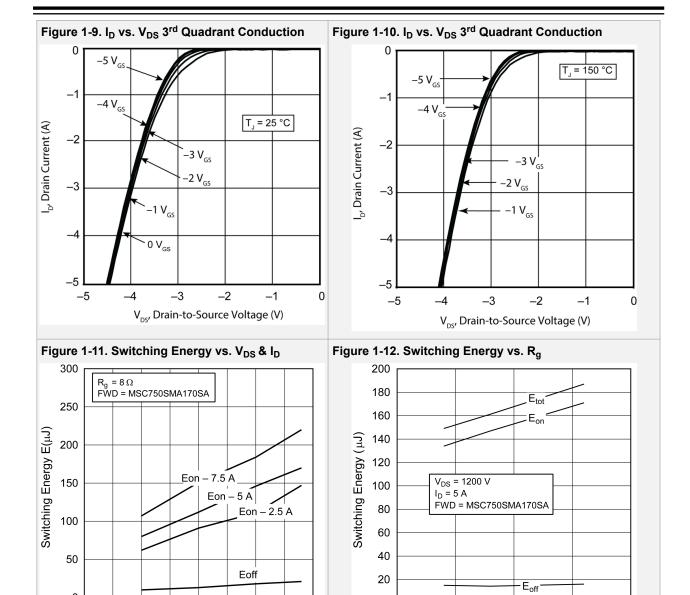


Figure 1-7. Capacitance vs. Drain-to-Source Voltage







700 800 900 1000 1100 1200 1300 1400

V_{DS}, Drain-to-Source Voltage (V)

0

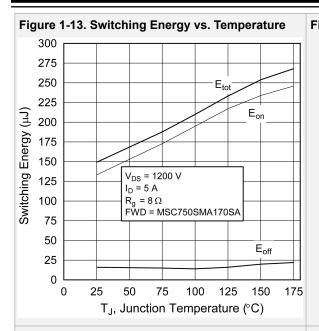
0

5

10

 $R_g(\Omega)$

20



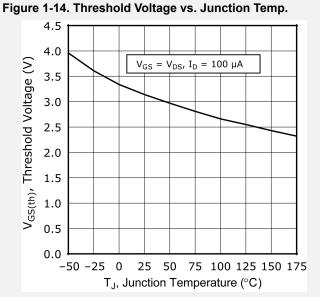
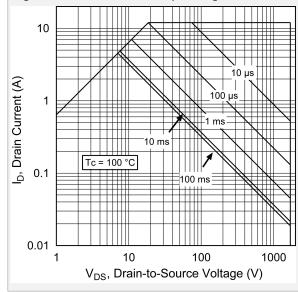
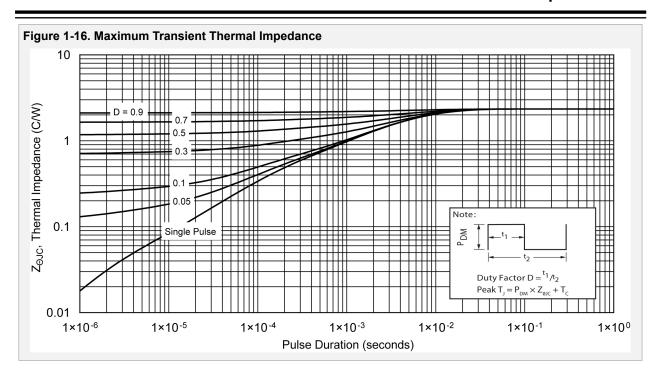


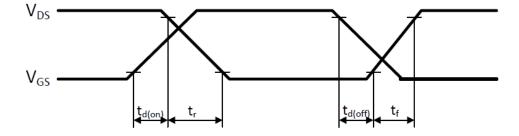
Figure 1-15. Forward Safe Operating Area





The following figure shows the switching waveform diagram of the MSC750SMA170SA device.

Figure 1-17. Switching Waveform



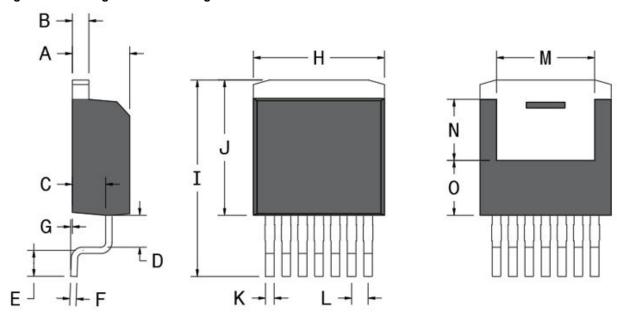
2. Package Specification

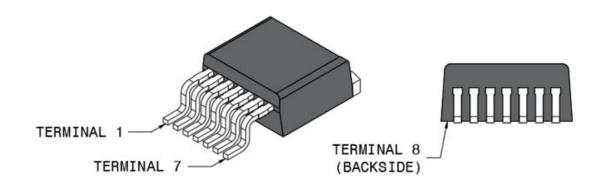
This section shows the package specification of the MSC750SMA170SA device.

2.1 Package Outline Drawing

The following figure illustrates the TO-263 7-lead package outline of the MSC750SMA170SA device.

Figure 2-1. Package Outline Drawing





The following table shows the TO-263 7-lead dimensions and should be used in conjunction with the package outline drawing.

Table 2-1. TO-263 Dimensions

Symbol	Min (mm)	Max (mm)	Min (in.)	Max (in.)
Α	4.30	4.57	0.169	0.180
В	1.17	1.40	0.046	0.055
С	2.50	2.70	0.098	0.106

MSC750SMA170SA

Package Specification

continued						
Symbol	Min (mm)	Max (mm)	Min (in.)	Max (in.)		
D	2.85	2.95	0.112	0.116		
E	2.32	2.70	0.091	0.106		
F	0.33	0.65	0.013	0.026		
G	0.00	0.25	0.00	0.010		
Н	10.13	10.23	0.399	0.403		
1	15.04	17.12	0.592	0.674		
J	10.19	10.80	0.401	0.425		
K	0.50	0.70	0.020	0.028		
L	1.27 BSC		0.050 BSC			
М	6.78	7.67	0.267	0.302		
N	4.66	4.81	0.183	0.189		
0	4.20	4.30	0.165	0.169		
Terminal 1	Gate					
Terminal 2	Source sense					
Terminal 3	Source					
Terminal 4	Source	Source				
Terminal 5	Source	Source				
Terminal 6	Source	ource				
Terminal 7	Source					
Terminal 8	Drain					

3. Revision History

Table 3-1. Revision History

Revision	Date	Description
Α	03/2022	Document created.

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